## **DISCRETE SEMICONDUCTORS**

# DATA SHEET

# **PDTC144T series** NPN resistor-equipped transistors; R1 = 47 k $\Omega$ , R2 = open

Product specification Supersedes data of 2004 Apr 06 2004 Aug 17





## **PDTC144T series**

#### **FEATURES**

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

#### **APPLICATIONS**

- · General purpose switching and amplification
- · Inverter and interface circuits
- Circuit driver.

#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	_	50	V
Io	output current (DC)	_	100	mA
R1	bias resistor	47	_	kΩ
R2	open	_	_	_

#### **DESCRIPTION**

NPN resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

#### **PRODUCT OVERVIEW**

TYPE NUMBER	PACK	AGE	MARKING CODE	PNP COMPLEMENT	
I THE NUMBER	PHILIPS EIAJ		WARKING CODE	PNP COMPLEMENT	
PDTC144TE	SOT416	SC-75	43	PDTA144TE	
PDTC144TEF	SOT490	SC-89	33	PDTA144TEF	
PDTC144TK	SOT346	SC-59	53	PDTA144TK	
PDTC144TM	SOT883	SC-101	E4	PDTA144TM	
PDTC144TS	SOT54 (TO-92)	SC-43	TC144T	PDTA144TS	
PDTC144TT	SOT23	-	*41 <sup>(1)</sup>	PDTA144TT	
PDTC144TU	SOT323	SC-70	*41 <sup>(1)</sup>	PDTA144TU	

#### Note

<sup>1. \* =</sup> p: Made in Hong Kong.

<sup>\* =</sup> t: Made in Malaysia.

<sup>\* =</sup> W: Made in China.

# NPN resistor-equipped transistors; R1 = 47 k $\Omega$ , R2 = open

## PDTC144T series

### SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL		PINNING
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION
PDTC144TS	1 R1 R1 3 MAM361	1 2 3	base collector emitter
PDTC144TE PDTC144TEF PDTC144TK PDTC144TT PDTC144TU	3 1 R1 2 Top view MDB270	1 2 3	base emitter collector
PDTC144TM	2 R1 3 1 Bottom view  MHCS07	1 2 3	base emitter collector

# NPN resistor-equipped transistors; R1 = 47 k $\Omega$ , R2 = open

## PDTC144T series

#### **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE	
I TPE NUMBER	NAME	DESCRIPTION	VERSION
PDTC144TE	_	plastic surface mounted package; 3 leads	SOT416
PDTC144TEF	_	plastic surface mounted package; 3 leads	SOT490
PDTC144TK	_	plastic surface mounted package; 3 leads	SOT346
PDTC144TM	_	leadless ultra small plastic package; 3 solder lands; body $1.0 \times 0.6 \times 0.5 \text{ mm}$	SOT883
PDTC144TS	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTC144TT	_	plastic surface mounted package; 3 leads	SOT23
PDTC144TU	_	plastic surface mounted package; 3 leads	SOT323

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	50	٧
V <sub>CEO</sub>	collector-emitter voltage	open base	_	50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	5	V
Io	output current (DC)		_	100	mA
I <sub>CM</sub>	peak collector current		_	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	SOT54	note 1	_	500	mW
	SOT23	note 1	_	250	mW
	SOT346	note 1	_	250	mW
	SOT323	note 1	_	200	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
	SOT416	note 1	_	150	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu m$  copper strip line.

# NPN resistor-equipped transistors; R1 = 47 k $\Omega$ , R2 = open

## PDTC144T series

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W
	SOT416	note 1	833	K/W

#### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu m$  copper strip line.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 50 V; I <sub>E</sub> = 0 A	_	_	100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = 30 \text{ V}; I_{B} = 0 \text{ A}$	_	_	1	μΑ
		$V_{CE} = 30 \text{ V}; I_{B} = 0 \text{ A}; T_{j} = 150 ^{\circ}\text{C}$	_	_	50	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0 \text{ A}$	_	_	100	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 1 \text{ mA}$	100	_	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = 10 \text{ mA}; I_B = 0.5 \text{ mA}$	_	_	150	mV
R1	input resistor		33	47	61	kΩ
C <sub>c</sub>	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = 10 \text{ V};$ f = 1 MHz	_	_	2.5	pF

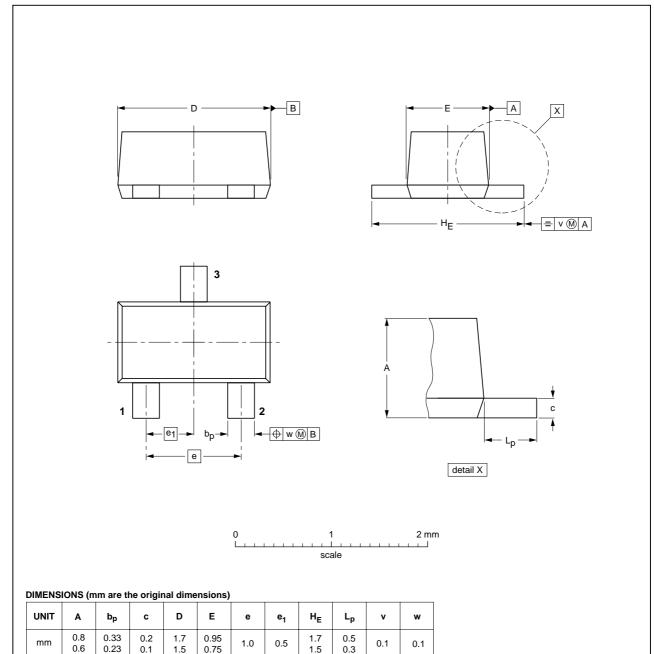
# NPN resistor-equipped transistors; R1 = 47 k $\Omega$ , R2 = open

## PDTC144T series

#### **PACKAGE OUTLINES**

#### Plastic surface mounted package; 3 leads

SOT490

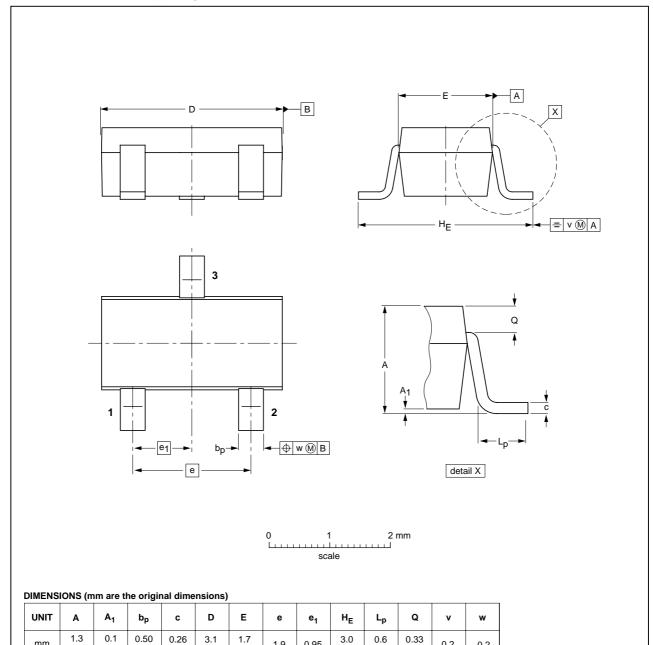


OUTLINE		REFER	ENCES	EUROPEAN	ICCUIT DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT490			SC-89		98-10-23	

## PDTC144T series

#### Plastic surface mounted package; 3 leads

**SOT346** 



OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT346		TO-236	SC-59		98-07-17	

0.95

0.2

0.2

1.9

2004 Aug 17 7

1.0

0.013

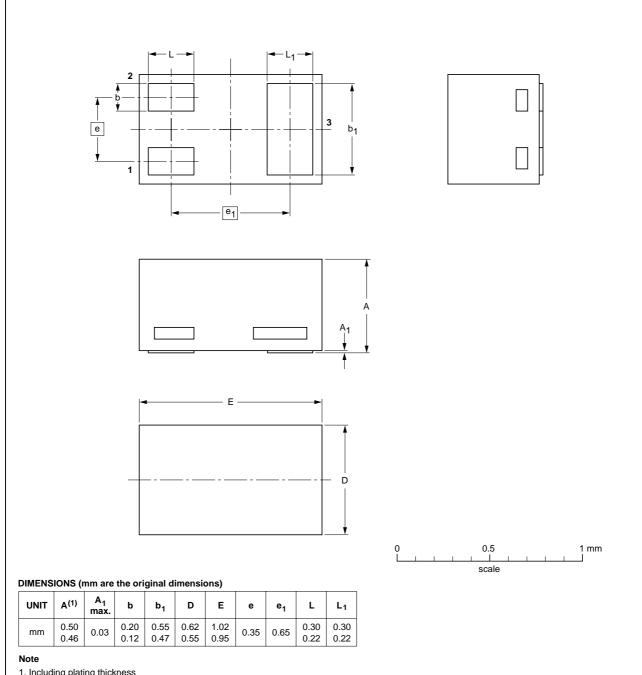
0.35

# NPN resistor-equipped transistors; R1 = 47 k $\Omega$ , R2 = open

## PDTC144T series

#### Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

**SOT883** 



1. Including plating thickness

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	1550E DATE	
SOT883			SC-101		<del>03-02-05</del> 03-04-03	

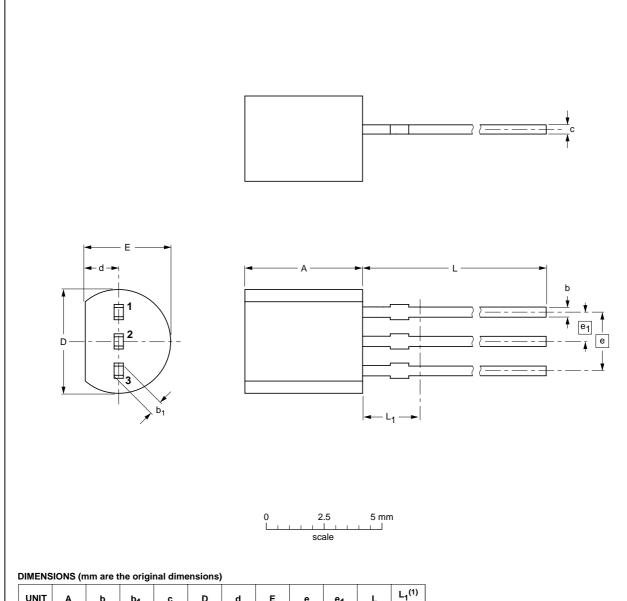
2004 Aug 17 8

# NPN resistor-equipped transistors; R1 = 47 k $\Omega$ , R2 = open

## PDTC144T series

#### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

#### Note

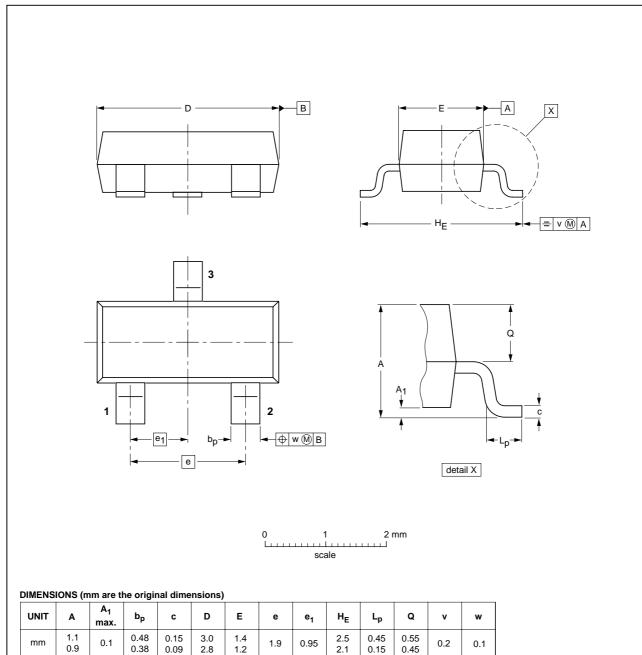
1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT54		TO-92	SC-43A		<del>97-02-28</del> 04-06-28	

## PDTC144T series

#### Plastic surface mounted package; 3 leads

SOT23

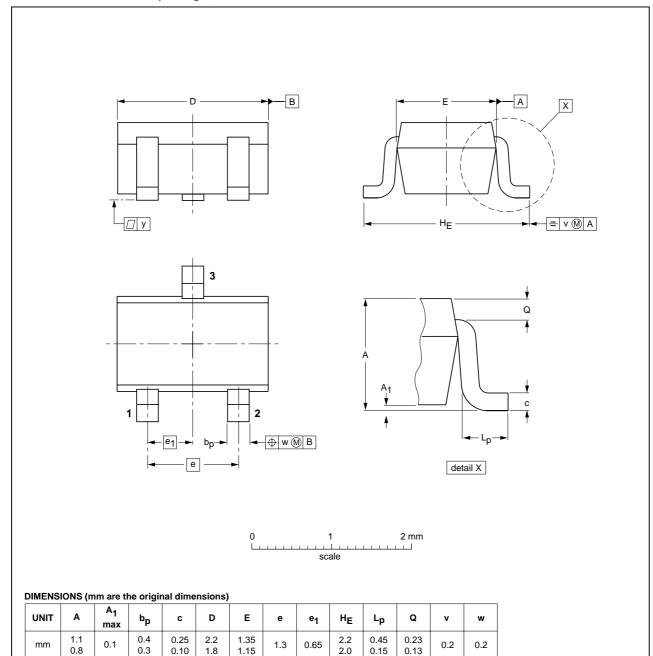


OUTLINE	REFERENCES				EUROPEAN	IOOUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT23		TO-236AB				<del>-97-02-28</del> 99-09-13

## PDTC144T series

#### Plastic surface mounted package; 3 leads

**SOT323** 

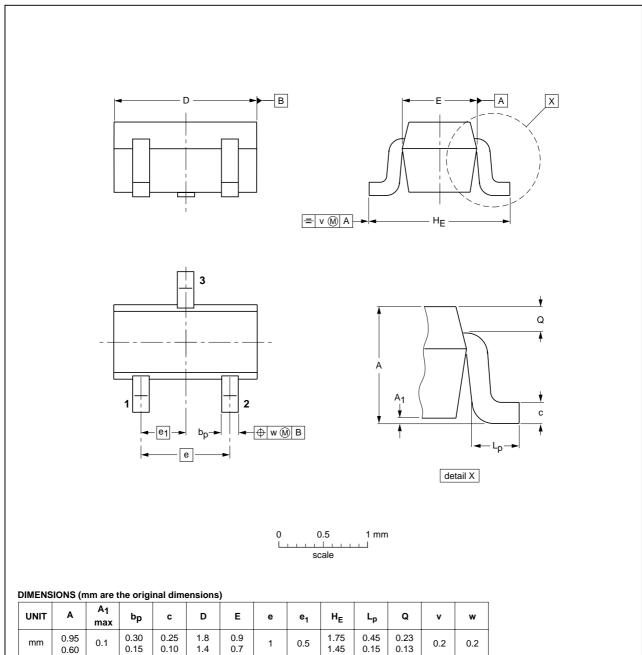


OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT323			SC-70			97-02-28

## PDTC144T series

#### Plastic surface mounted package; 3 leads

**SOT416** 



OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT416			SC-75			97-02-28

## NPN resistor-equipped transistors; R1 = 47 k $\Omega$ , R2 = open

#### PDTC144T series

#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

#### **DEFINITIONS**

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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